Gas Plasma Dry Cleaner

Plasma Surface Treatment Device

PDC200/210/510

High frequency 300W 500W output (PDC200) (PDC210/510)

Stage size

250×170mm 410×210mr PDC200/210) (PDC510)

Small and compact, suitable for R&D purposes

Features

- Simple and compact plasma surface treatment device
- RIE (Reactive Ion Etching) Plasma mode, with DP (Direct Plasma) mode as option
- Excellent electrode structure for plasma uniformity
- Simple touch panel system

Applications

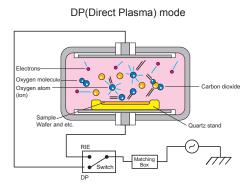
- Plasma processing of CSP, BGA, COB substratum
- Removal of organic films and metal oxidized films
- Dry cleaning of printed circuit board
- Surfactant process
- LED assembly
- For R&D



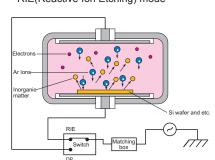
Chamber



Diagram



RIE(Reactive Ion Etching) mode



Specifications

| Model | PDC200 | PDC210 | PDC510 |
|-------------------------------|-----------------------------------|-------------------------------|----------------------|
| Plasma mode | RIE (DP mode option) | | RIE/DP selectable |
| Electrode structure | Parallel flat stage plate | | |
| Vacuum gauge | Capacitance manometer | | |
| High frequency output | Max 300W | Max 500W | |
| Oscillation frequency | 13.56MHz Quartz oscillator | | |
| Output setting method | Manual setting on LCD touch panel | | |
| Matching method | Auto tuning | | |
| Controller | Programmable | | |
| Display | LCD touch panel | | |
| Chamber size | W400 × D250 × H150mm | | W500 x D300 x H200mm |
| Stage size | W250 × D170mm | | W410 x D210mm |
| Chamber material | Aluminum | | |
| Reaction gas | 2 systems (Argon, Oxygen) | | |
| Purge gas | Nitrogen or dry air | | |
| Reaction gas flow control | Flow meter | Mass flow controller | |
| Rotary vacuum pump (optional) | ~345L/min. | | ~500L/min. |
| External dimensions | W540×D600×H600mm | W540×D600×H600mm | W700xD700xH700mm |
| Weight | ~100kg | ~105kg | 180kg |
| Power source | Single phase AC115V 50/60Hz | 3-phase AC200V~AC240V 50/60Hz | |